

### Description

The GT55N06 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

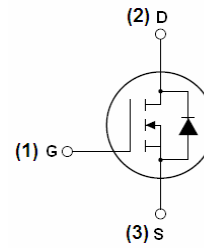
### General Features

| VDSS | RDS(ON)<br>@10V (typ) | RDS(ON)<br>@4.5V (typ) | ID  |
|------|-----------------------|------------------------|-----|
| 60V  | 6.8mΩ                 | 9.5 mΩ                 | 53A |

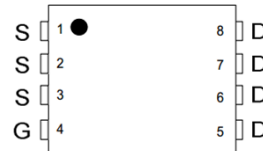
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability
- RoHS Compliant

### Application

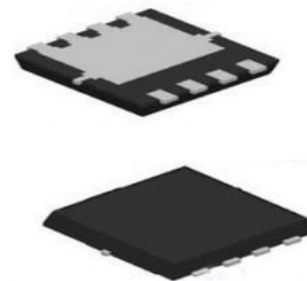
Synchronous Rectification in DC/DC and AC/DC Converters  
Industrial and Motor Drive applications



Schematic diagram



Marking and pin assignment



DFN 5x6-8L

### Ordering Information

| Part Number | Marking | Case      | Packaging    |
|-------------|---------|-----------|--------------|
| GT55N06     | GT55N06 | DFN5X6-8L | 2500pcs/Reel |

### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

| Parameter                                      | Symbol         | Maximum                   | Units            |
|--|----------------|---------------------------|------------------|
| Drain-Source Voltage                           | $V_{DS}$       | 60                        | V                |
| Gate-Source Voltage                            | $V_{GS}$       | $\pm 20$                  | V                |
| Continuous Drain Current <sup>G</sup>          | $I_D$          | $T_A = 25^\circ\text{C}$  | 53               |
|  |                | $T_A = 100^\circ\text{C}$ | 34               |
| Pulsed Drain Current <sup>C</sup>              | $I_{DM}$       | 110                       | A                |
| Avalanche energy $L=0.5\text{mH}$ <sup>C</sup> | $E_{AS}$       | 195                       | mJ               |
| Power Dissipation <sup>A</sup>                 | $P_{DSM}$      | $T_A = 25^\circ\text{C}$  | 70               |
|  |                | $T_A = 70^\circ\text{C}$  | 28               |
| Junction and Storage Temperature Range         | $T_J, T_{STG}$ | -55 to 150                | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter                                  | Symbol          | Maximum | Units              |
|--|-----------------|---------|--------------------|
| Maximum Junction-to-Ambient <sup>A</sup>   | $R_{\theta JA}$ | 14      | $^\circ\text{C/W}$ |
| Maximum Junction-to-Ambient <sup>A D</sup> |                 | 40      | $^\circ\text{C/W}$ |
| Maximum Junction-to-Case                   | $R_{\theta JC}$ | 1.3     | $^\circ\text{C/W}$ |

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

| Symbol                      | Parameter  | Conditions  | Min | Typ        | Max         | Units |
|-----------------------------|--|---|-----|------------|-------------|-------|
| <b>STATIC PARAMETERS</b>    |  |   |     |            |             |       |
| BV <sub>DSS</sub>           | Drain-Source Breakdown Voltage                     | I <sub>D</sub> =250μA, V <sub>GS</sub> =0V  | 60  | 65         |             | V     |
| I <sub>DSS</sub>            | Zero Gate Voltage Drain Current                    | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V<br>T <sub>J</sub> =55°C                         |     |            | 1<br>5      | μA    |
| I <sub>GSS</sub>            | Gate-Body leakage current                          | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V  |     |            | ±100        | nA    |
| V <sub>GS(th)</sub>         | Gate Threshold Voltage                             | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                  | 1.1 | 1.7        | 2.5         | V     |
| R <sub>DS(on)</sub>         | Static Drain-Source On-Resistance                  | V <sub>GS</sub> =10V, I <sub>D</sub> =20A<br>V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A   |     | 6.8<br>9.5 | 8.2<br>12.0 | mΩ    |
| g <sub>FS</sub>             | Diode Forward Voltage                              | V <sub>DS</sub> =5V, I <sub>D</sub> =20A  | 30  |            |             | S     |
| V <sub>SD</sub>             | Diode Forward Voltage                              | I <sub>S</sub> =20A, V <sub>GS</sub> =0V  |     | 0.85       | 0.99        | V     |
| I <sub>S</sub>              | Maximum Body-Diode Continuous Current <sup>G</sup> |   |     |            | 53          | A     |
| <b>DYNAMIC PARAMETERS</b>   |  |   |     |            |             |       |
| C <sub>iss</sub>            | Input Capacitance                                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, f=1MHz   |     | 1988       |             | pF    |
| C <sub>oss</sub>            | Output Capacitance                                 |   |     | 470        |             | pF    |
| C <sub>rss</sub>            | Reverse Transfer Capacitance                       |   |     | 14         |             | pF    |
| R <sub>g</sub>              | Gate resistance                                    | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz  |     | 1.6        |             | Ω     |
| <b>SWITCHING PARAMETERS</b> |  |   |     |            |             |       |
| Q <sub>g(10V)</sub>         | Total Gate Charge                                  | V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =20A                           |     | 31         |             | nC    |
| Q <sub>g(4.5V)</sub>        | Total Gate Charge                                  |   |     | 16         |             | nC    |
| Q <sub>gs</sub>             | Gate Source Charge                                 |   |     | 6          |             | nC    |
| Q <sub>gd</sub>             | Gate Drain Charge                                  |   |     | 5          |             | nC    |
| t <sub>D(on)</sub>          | Turn-on Delay Time                                 | V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =2.5Ω,<br>R <sub>GEN</sub> =3Ω |     | 10.5       |             | ns    |
| t <sub>r</sub>              | Turn-on Rise Time                                  |   |     | 4.5        |             | ns    |
| t <sub>D(off)</sub>         | Turn-off Delay Time                                |   |     | 29.5       |             | ns    |
| t <sub>f</sub>              | Turn-off Fall Time                                 |   |     | 8          |             | ns    |
| t <sub>rr</sub>             | Body Diode Reverse Recovery Time                   | I <sub>F</sub> =20A, di/dt=500A/μs  |     | 17         |             | ns    |
| Q <sub>rr</sub>             | Body Diode Reverse Recovery charge                 | I <sub>F</sub> =20A, di/dt=500A/μs  |     | 58         |             | nC    |

A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The Power dissipation P<sub>D(SM)</sub> is based on R<sub>θJA</sub> ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T<sub>J(MAX)</sub>=150° C.

D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to case R<sub>θJC</sub> and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

## Typical Performance Characteristics

Fig 1: Output Characteristics

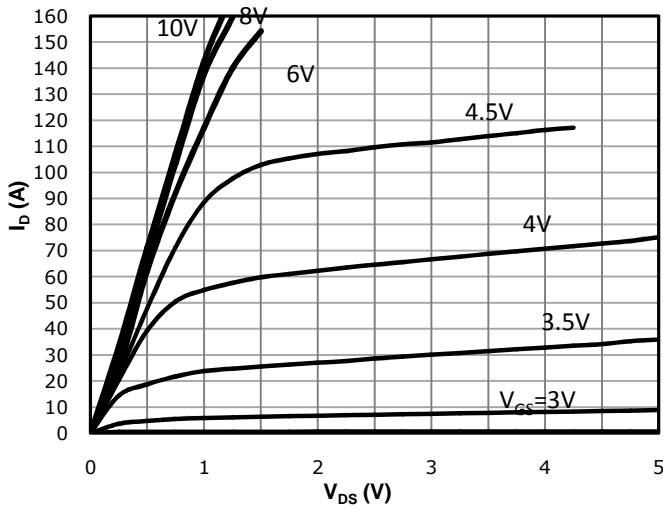


Fig 2: Transfer Characteristics

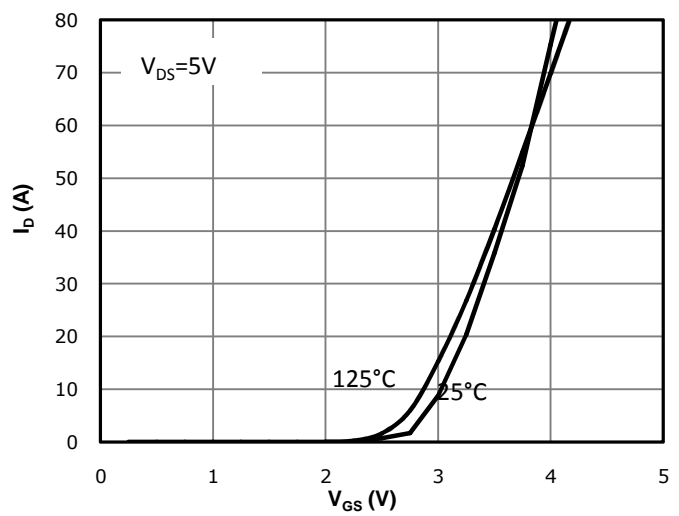


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

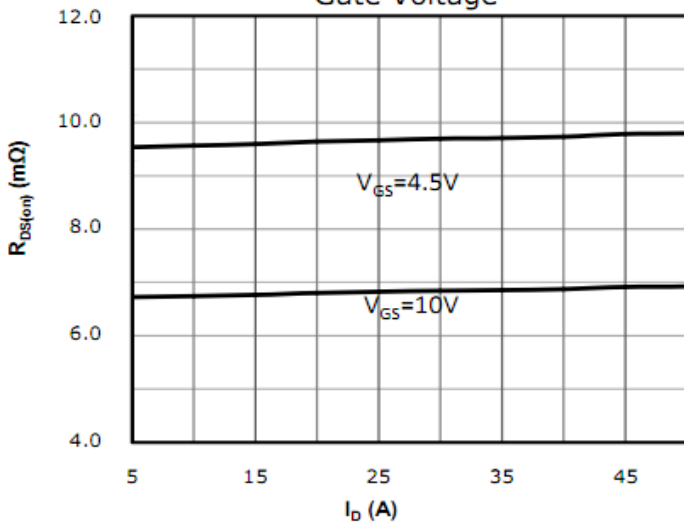


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

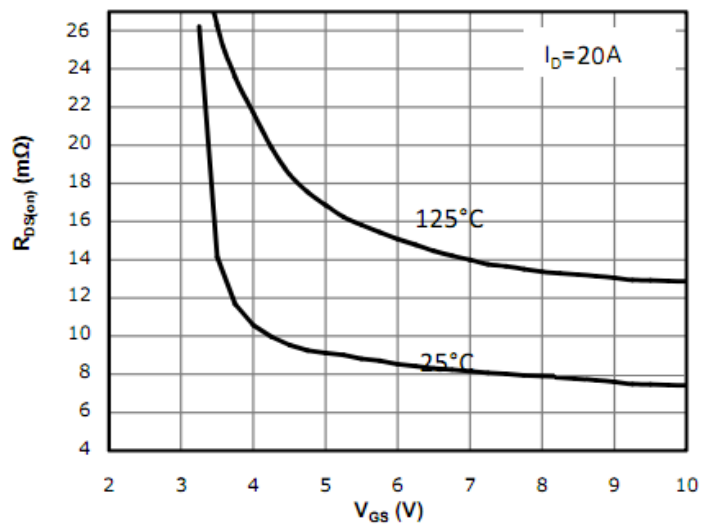


Fig 5:  $R_{DS(on)}$  vs. Temperature

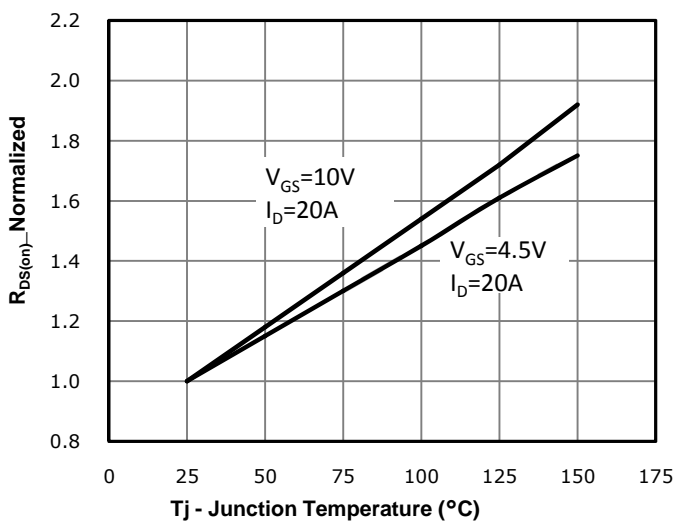


Fig 6: Capacitance Characteristics

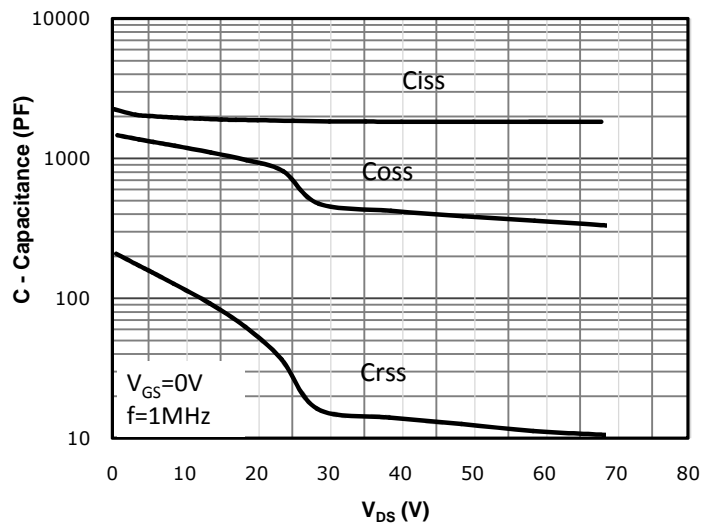


Fig 7: Gate Charge Characteristics

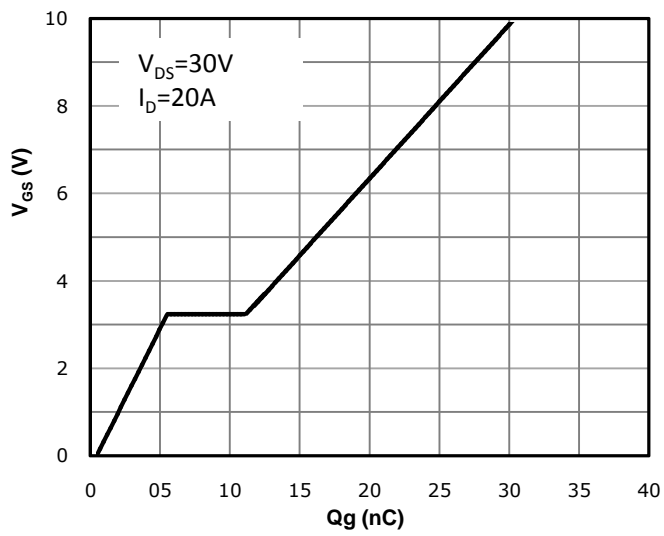


Fig 8: Body-diode Forward Characteristics

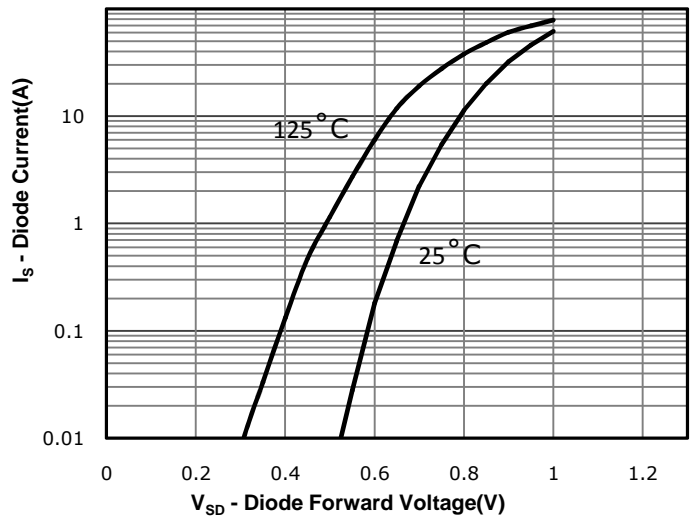


Fig 9: Power Dissipation

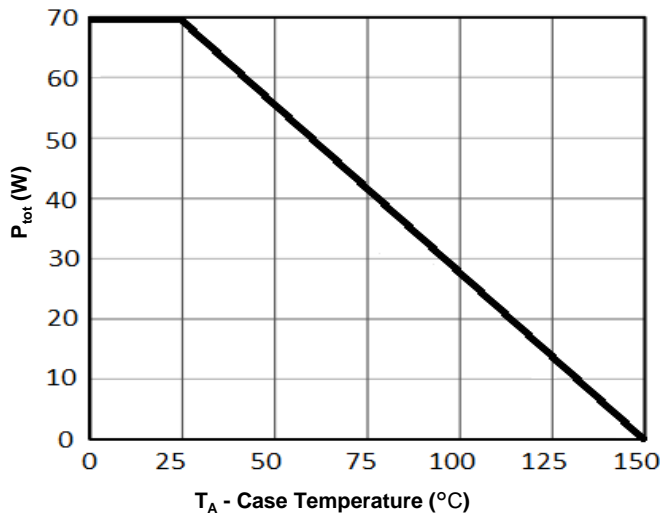


Fig 10: Drain Current Derating

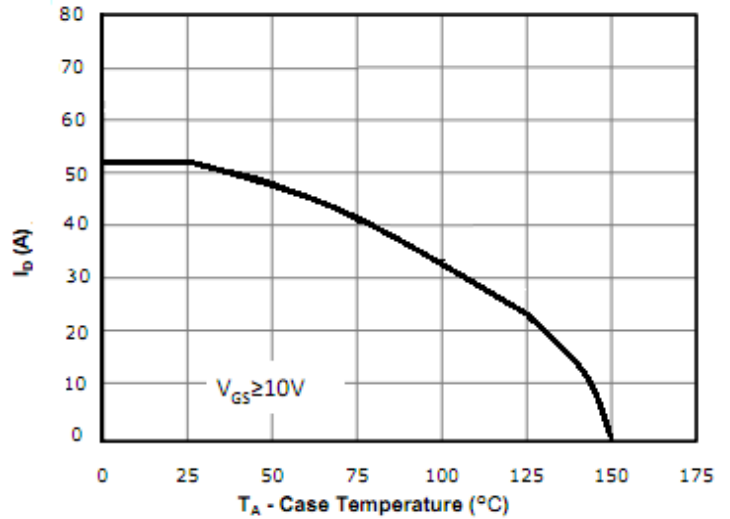


Figure A: Gate Charge Test Circuit & Waveforms

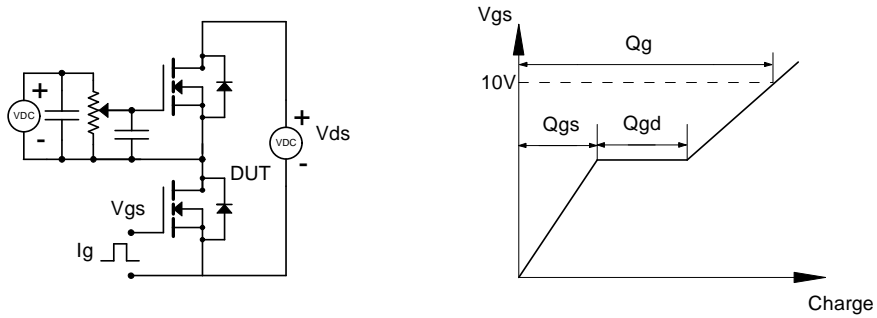


Figure B: Resistive Switching Test Circuit & Waveforms

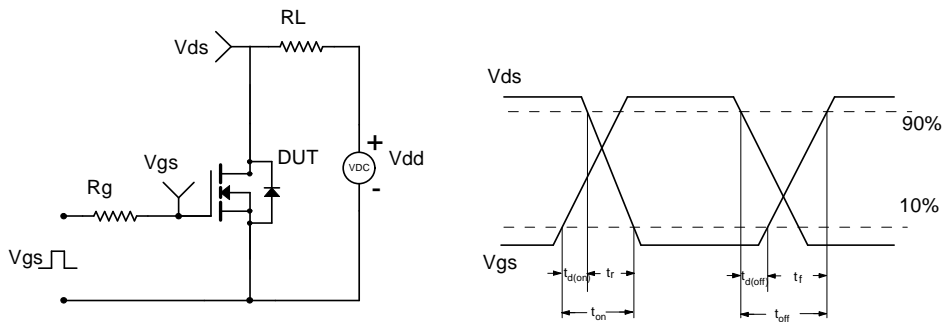


Figure C: Unclamped Inductive Switching (UIS) Test

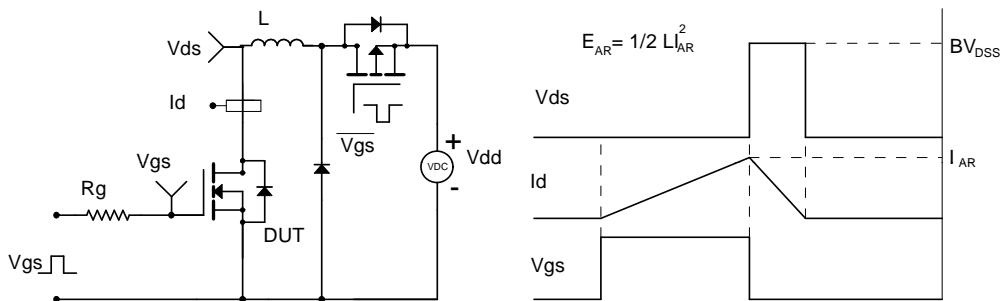
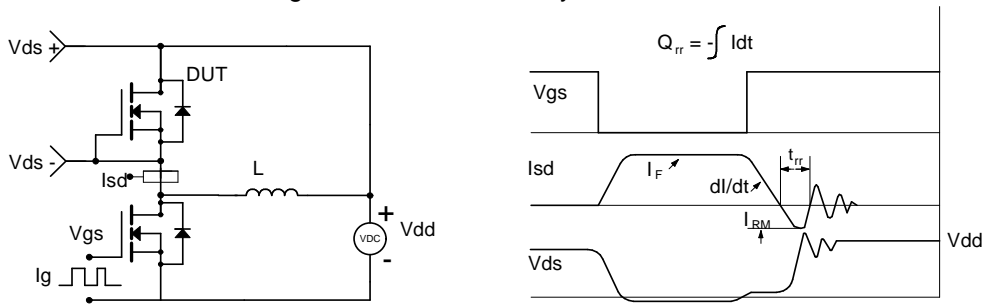
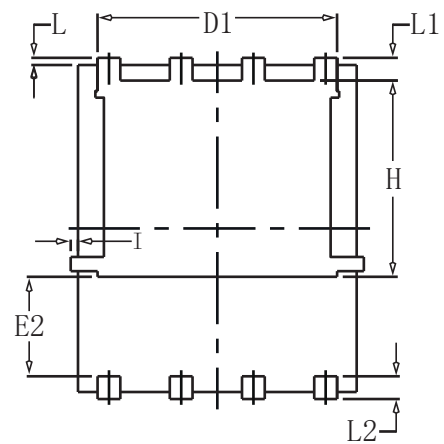
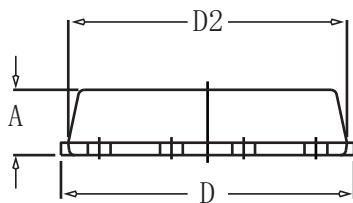
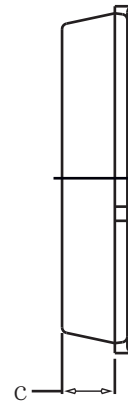
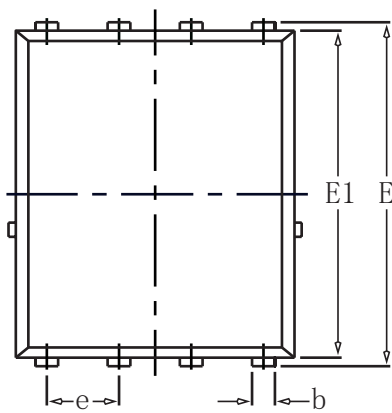


Figure D: Diode Recovery Test Circuit & Waveforms



DFN5X6-8L Package information



| SYMBOL | COMMON   |       |          |        |
|--------|----------|-------|----------|--------|
|        | MM       |       | INCH     |        |
|        | MIN      | MAX   | MIN      | MAX    |
| A      | 1.03     | 1.17  | 0.0406   | 0.0461 |
| b      | 0.34     | 0.48  | 0.0134   | 0.0189 |
| c      | 0.824    | 0.970 | 0.0324   | 0.0382 |
| D      | 4.80     | 5.40  | 0.1890   | 0.2126 |
| D1     | 4.11     | 4.31  | 0.1618   | 0.1697 |
| D2     | 4.80     | 5.00  | 0.1890   | 0.1969 |
| E      | 5.59     | 6.15  | 0.2343   | 0.2421 |
| E1     | 5.65     | 5.85  | 0.2224   | 0.2303 |
| E2     | 1.60     | -     | 0.0630   | -      |
| e      | 1.27 BSC |       | 0.05 BSC |        |
| L      | 0.05     | 0.25  | 0.0020   | 0.0098 |
| L1     | 0.38     | 0.50  | 0.0150   | 0.0197 |
| L2     | 0.38     | 0.50  | 0.0150   | 0.0197 |
| H      | 3.30     | 3.50  | 0.1299   | 0.1378 |
| I      | -        | 0.18  | -        | 0.0070 |

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